

Date: August 19, 2022

PCN No#: 081922-2

PCN Title: Additional a new wafer source for MCG08P06HE3-TP

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Micro Commercial Components Corp(MCC). We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local sales representative to acknowledge receipt of this PCN.

If you have any questions about PCN's products, please contact your local sales representative.

Sincerely,

MCC PCN Team



INITIAL PRODUCT CHANGE NOTICE

Notification Date	Implementation Date	Effective Date Code	Change Type	PCN No
August 19, 2022	August 19, 2022	2236	Major	081922-2
		TITLE		
Additional a new wafer so	ource for MCG08P06HE3-TI	P		
	DE	SCRIPTION OF CHANGE		
To establish dual wafer so	ource for product MCG08P0	06HE3-TP to increase produ	ction capacity for market	demand.
		IMPACT		
	aracteristic and its reliability omparison;Table B: X-RAY	performance Comparison;Table C: Typ.F	T Data	
	P	RODUCTS AFFECTED		
MCG08P06HE3-TP				
		WEB LINKS		
Terms And Conditions:	https://www.	https://www.mccsemi.com/Home/TermsAndConditions		
For More Information Co	ontact: https://www	https://www.mccsemi.com/Contact/Index		
Products:	https://www	https://www.mccsemi.com/ProductCategories		
	-	DISCLAIMER		



Table A - Marking Code Comparison.				
Item	Current	New		
Marking	MCC 08P06 2137	MCC. 08P06 2223		

	Table B - X-RAY Compar	ison.
Item	Current	New
X-RAY		

Table C - Typ.FT Data					
Parameter	Test Conditions	Spec	Current (Typ.)	New(Typ.)	Unit
V _{(BR)DSS}	V _{GS} =0V, I _D =-250μA	-60	-69	-69	V
R _{DS(on)}	V _{GS} =-10V, I _D =-3A	28.4	23	20	mΩ
$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_{D}=-250\mu A$	-1~-3	-1.8	-1.8	V
V _{SD}	V_{GS} =0V, I_{S} =-3A	-1.3	0.8	0.8	V



Reliability Report

Part Number: MCG08P06HE3-TP

Date: 2022-08-19

Test Results

Test Item	Conditions	Duration	Quantity	Rejects
TEST Pre- and Post-Stress Electrical Test	T _a = 25 °C	N/A	all parts	see below
PC Preconditioning	JESD22A-113 Bake T_a = 125 °C Soak T_a = 85 °C, RH = 85%Reflow soldering	24 hours 168 hours 3 cycles	3 08Pcs	0
HTRB High Temperature Reverse Bias	JESD22-A108 $T_j = T_{jmax}, V_R > 80\% VDSS$	1000 hours	77Pcs	0
TC Temperature Cycling	JESD22-A104 -55 °C to T _{jmax}	1000 cycles	77Pcs	0
AC Autoclave	JESD22-A102 T _a = 121 °C, RH = 100 % Pressure = 2atm	96 hours	77Pcs	0
H3TRB High Humidity High Temperature Reverse Bias	JESD22-A101 $T_a = 85$ °C, RH = 85%, $V_R > 80$ % VDSS	1000 hours	77Pcs	0
IOL Intermittent Operating Life	MIL-STD-750 Method 1037 $t_{on} = t_{off}$, devices powered to insure $\Delta T_j = 100$ °C for 15000 cycles	1000 hours	77Pcs	0
RSH Resistance to Solder Heat	JESD22-A111 / JESD22-B106 260 °C (+5,-0) °C	10 s	77Pcs	0
SD Solderability	J-STD-002 245 °C ± 5 °C	3 s	77Pcs	0
LTSL Low Temperature Storage Life	JESD22-A119 Ta≤-55℃	1000 hours	77Pcs	0
HTSL High Temperature Storage Life	JESD22-A103 Ta≥150℃	1000 hours	77Pcs	0
HTGB High Temperature Gate Bias	JESD22-A108 150°C ,100%VGS	1000 hours	77Pcs	0